Printed Circuit Boards
Interconnection Carriers

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
04	162	FR4	70	L71.105	P18_10	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_162_FR4_70_L71.105_p18_10

Layers	in µ	Material	Build-Up	Assembly
Layer-1	70µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	
Layer-2	105µ	Copper		A1
	710µ	L-FR4		
Layer-3	105µ	Copper		
	180µ	Prepreg		
	100µ	Prepreg		
Layer-99	70µ	Copper		

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